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RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 1756
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79007

Koichi KAWAMURA, et al.

Appln. No.: 10/735,769

Group Art Unit: 1756

Confirmation No.: 3973

Examiner: Daborah Chacko Davis

Filed: December 16, 2003

For: PATTERN FORMING METHOD AND SUBSTANCE ADHERENCE PATTERN MATERIAL

RESPONSE UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 27, 2006, please consider the remarks as submitted herewith on the accompanying pages.

REMARKS

Claims 1-23 are all the claims pending in the application.

I. Response to Claim Rejection Under 35 U.S.C. § 102

Claims 1-23 are rejected under 35 U.S.C. § 102(e) as allegedly being anticipated by U.S. Patent No. 6,919,158 (Kawamura et al). The Examiner takes the position that the disclosure of Kawamura et al at column 23, lines 1-50 and column 24, lines 1-50 of selectively exposing the hydrophilic compound to exposure radiation causing polymerization and that the